



Q1 FY2025 Financial Announcement

January – March 2025

May 14, 2025

Security Code 6266

Company Guide



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Q1 FY2025 Consolidated Financial Summary

Net sales

7,516

Million Yen

YoY Change +27.3 %

Operating income

1,210

Million Yen

YoY Change +112.2 %

Ordinary income

1,176

Million Yen

YoY Change + 77.7 %

Net income(*)

855

Million Yen

YoY Change +101.3 %

■ Overview

- Compared to the previous period, both revenue and profit increased. Against the plan, sales were generally in line, while profit exceeded expectations. Although there were delays in inspection approvals in Process equipment business, Surface treatment equipment business progressed steadily.
- The order situation shows that transfer equipment continues to perform steadily, and semiconductor equipment is generally within expectations. In other businesses, there are inquiries, but orders tend to be delayed.

| (Millions of yen) | FY2024 Q1 | FY2025 Q1 | | YoY change (%) | FY2025 estimates | cf. Plan |
|---|-----------|-----------|---------------------|----------------|------------------|----------|
| | | Actual | Net sales ratio (%) | | | |
| Net sales | 5,905 | 7,516 | — | 27.3 | 41,000 | 18.3 |
| Gross profit | 1,883 | 2,606 | 34.7 | 38.4 | — | — |
| Operating income | 570 | 1,210 | 16.1 | 112.3 | 5,000 | 24.2 |
| Ordinary income | 662 | 1,176 | 15.7 | 77.6 | 5,100 | 23.1 |
| Net income attributable to owners of parent | 425 | 855 | 11.4 | 101.2 | 3,500 | 24.4 |

Trend in Net sales and Operating profit

■ Net sales
■ Operating income



| (Millions of yen) | FY2024 Actual | FY2025 Q1 | YoY change |
|-------------------------------|---------------|---------------|-------------|
| Current assets | 40,731 | 40,391 | △340 |
| Non-current assets | 8,469 | 8,677 | 208 |
| Property, plant and equipment | 7,385 | 7,537 | 152 |
| Intangible assets | 156 | 167 | 11 |
| Investments and other assets | 927 | 971 | 44 |
| Total assets | 49,200 | 49,068 | △132 |
| Current Liabilities | 17,696 | 17,624 | △72 |
| Non-Current Liabilities | 6,861 | 7,363 | 502 |
| Total liabilities | 24,557 | 24,988 | 431 |
| Total net assets | 24,642 | 24,080 | △562 |
| Equity ratio | 49.1% | 48.2% | △0.9P |

Major change

Current Assets (Millions of yen)

| | |
|---|------|
| Cash and deposits | △216 |
| Notes and accounts receivable - trade | +756 |
| Electronically recorded monetary claims - operating | △948 |
| Inventories | +440 |
| Other | △377 |

Current Liabilities

| | |
|---|--------|
| Electronically recorded obligations - operating | △1,849 |
| Short-term borrowings | +298 |
| Contract liabilities | +2,337 |
| Income taxes payable | △768 |

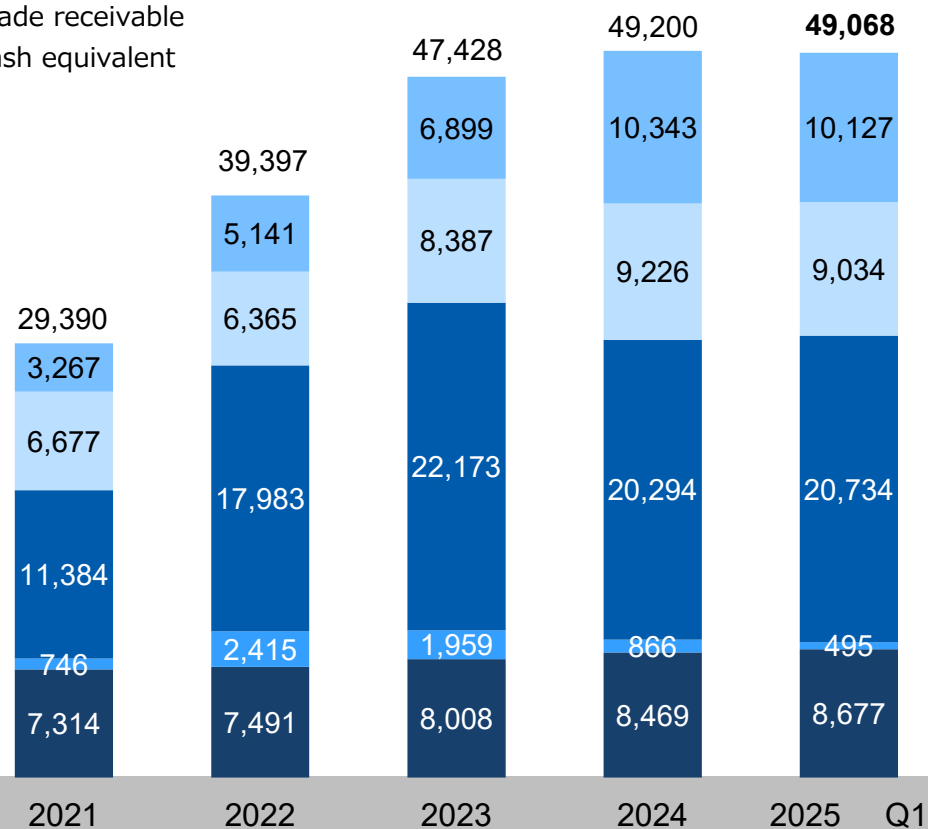
Non-Current Liabilities

| | |
|----------------------|------|
| Long-term borrowings | +543 |
|----------------------|------|

Assets

(Millions of yen)

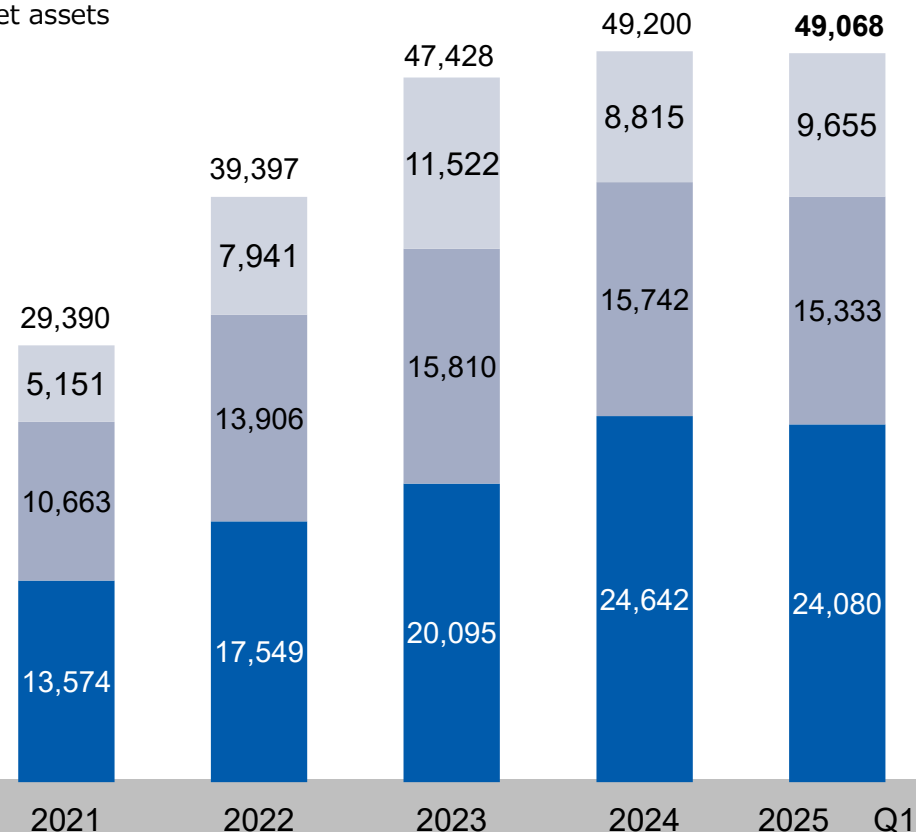
- Noncurrent assets
- Other current assets
- Investors
- Trade receivable
- Cash equivalent



Liabilities/Equity

(Millions of yen)

- Interest-bearing debt
- Other liabilities
- Net assets





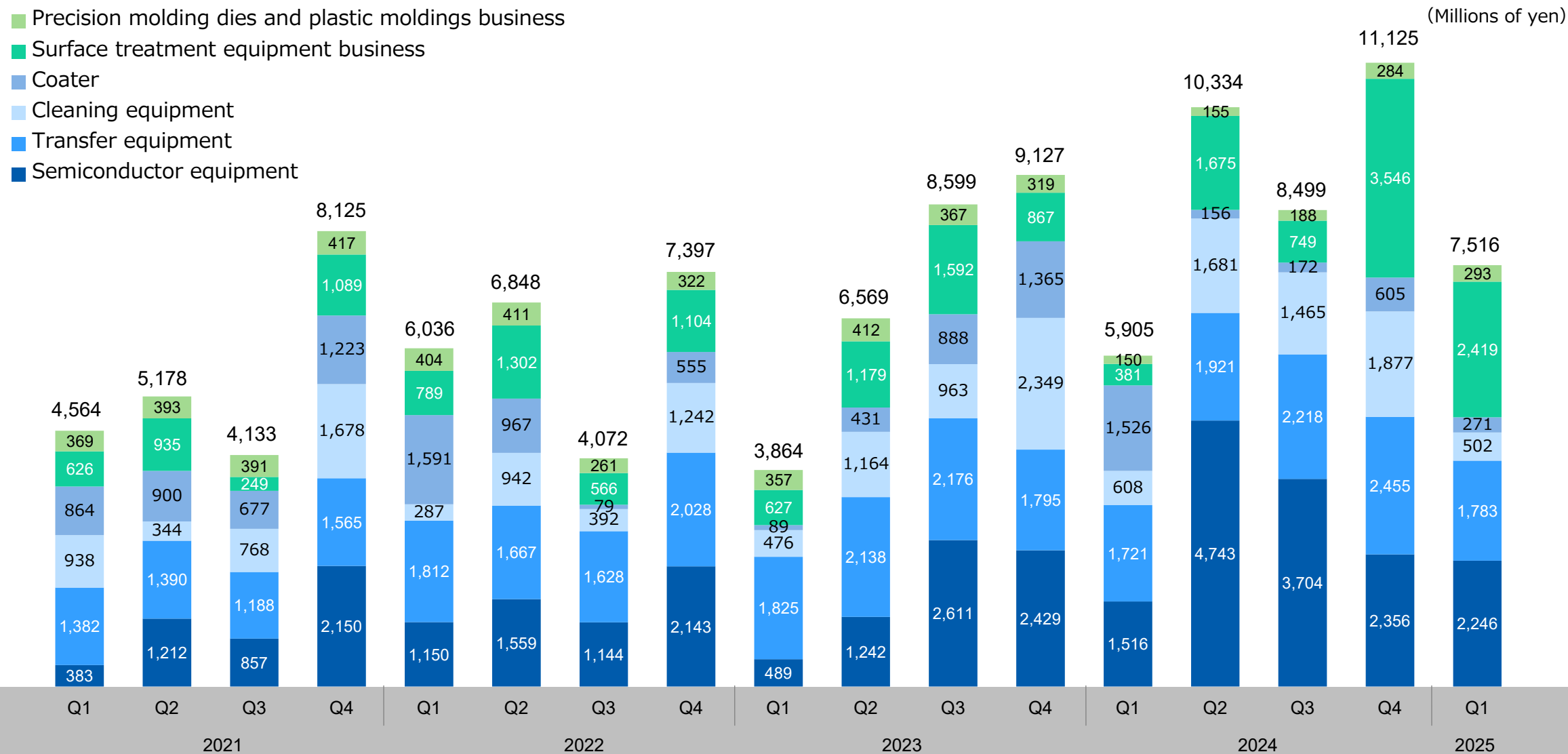
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Q1 FY2025 Segment Information

→ Net Sales and Operating Profit by Segment

| (Millions of yen) | | FY2024 Actual | FY2025 Q1 Actual | YoY change(%) | FY2025 Initial estimates | cf. Plan (%) | |
|--|---|------------------|---------------------|------------------|-----------------------------|--------------|------|
| Process equipment business | Net sales | 5,374 | 4,803 | △10.6 | 33,000 | 14.6 | |
| | Operating income | 730 | 752 | 3.0 | 4,500 | 16.7 | |
| | <div><div></div>Semiconductor equipment</div> | Net sales | 1,516 | 2,246 | 48.1 | 18,200 | 12.3 |
| | <div><div></div>Transfer equipment</div> | Net sales | 1,721 | 1,783 | 3.6 | 9,300 | 19.2 |
| | <div><div></div>Cleaning equipment</div> | Net sales | 608 | 502 | △17.4 | 3,700 | 13.6 |
| | <div><div></div>Coater</div> | Net sales | 1,526 | 271 | △82.2 | 1,800 | 15.0 |
| Precision molding dies and plastic moldings business | Net sales | 150 | 293 | 95.3 | 1,100 | 26.6 | |
| | Operating income | △52 | 38 | — | 50 | 76.0 | |
| Surface treatment equipment business | Net sales | 381 | 2,419 | 534.7 | 6,900 | 35.0 | |
| | Operating income | △131 | 394 | — | 450 | 87.6 | |
| Elimination of inter-segment transactions | | Operating income | △83 | △95 | — | — | |
| Total | Net sales | 5,905 | 7,516 | 27.3 | 41,000 | 18.3 | |
| | Operating income | 570 | 1,210 | 112.2 | 5,000 | 24.2 | |

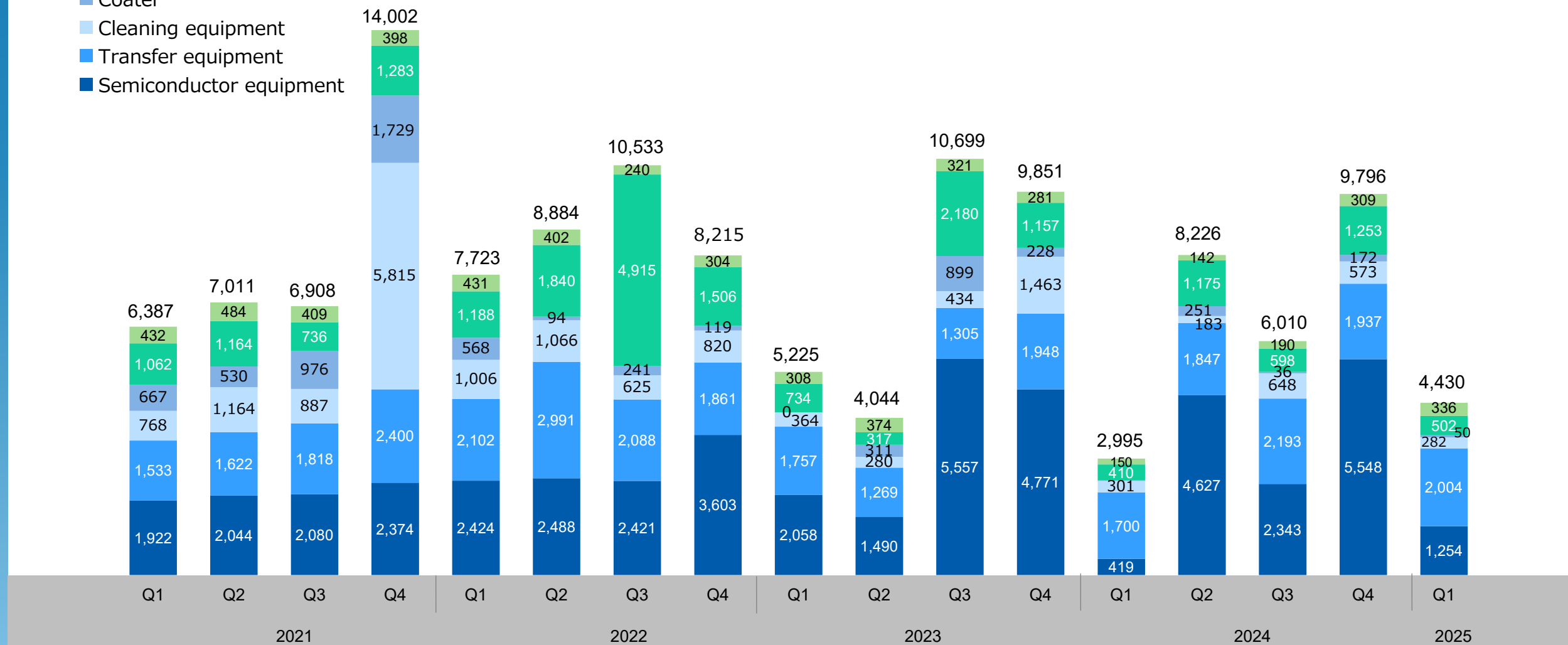
Trend in Net sales by Segment



Trend in Sales Orders by Segment

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

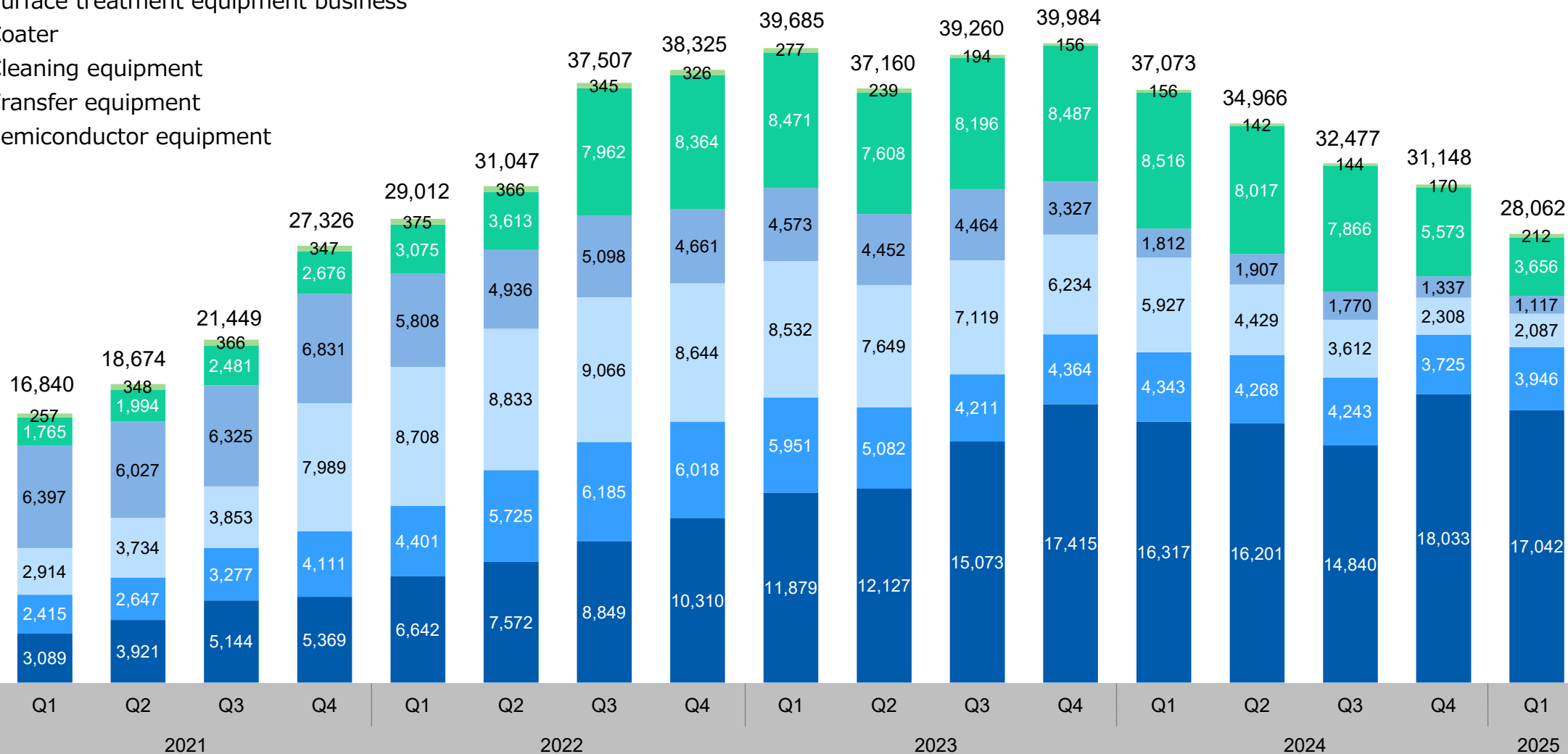
(Millions of yen)



Trend in Order Backlog by Segment

- Prescision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

(Millions of yen)





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Business Environment

- As for semiconductor manufacturing equipment, no orders were received for advanced packaging projects in Q1, but this is considered to be a matter of timing. For equipment related to power semiconductors, inquiries have started to emerge for investments planned from 2026 onward, although it is expected to take more time before they turn into actual orders.
- In transfer equipment, the impact of market conditions in the memory and logic sectors still remains, but there is a gradual recovery trend. However, order volumes by country continue to fluctuate on a monthly basis.
- There are inquiries for slurry supply systems, but users are taking time to make investment decisions. We are currently working to secure these orders with certainty. Regarding cleaning equipment, new project discussions are gradually emerging, but the investment timing is expected to be after 2026.
- For PLP equipment, there have been inquiries from regions such as Taiwan. We are working to ensure that these turn into confirmed orders. We expect the market to expand in the future.
- For surface treatment equipment, there are ongoing inquiries, but many of the projects are scheduled for investment in the latter half of 2026 or later, so it is expected to take time before they turn into orders. Meanwhile, delivery of the previously delayed substrate transfer-related equipment is now progressing.

| | |
|-------------------------------|---|
| Company name | TAZMO Co., Ltd. |
| Established | February 26, 1972 |
| Head office | 5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan |
| Capital | 3,556,890,682 yen |
| Total number of issued shares | 14,842,354 |
| Number of shareholders | 8,903 (As of December 31, 2024) |
| Number of employees | Non-consolidated 414 Consolidated 1,163 (As of December 31, 2024) |
| Business content | Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, LCD Manufacturing Equipment,UV Laser Equipment, Plating Equipment, Mold・Resin Molding, Plating/Circuit formation Equipment for PCB |

Domestic locations, Subsidiaries

Okayama-shi, Okayama
Head office

Izumo-shi, Shimane
Facility Ci., Ltd. Izumo Laboratory

Ibara-shi, Okayama
TAZMO Plant No.1
TAZMO Plant No.3
TAZMO Plant No.5
Quark Technology Co., Ltd.
PRETEC Co., Ltd.

Shinjuku-ku, Tokyo
Tokyo office

Sagamihara, Kanagawa
Facility Co., Ltd.

Global Network

Doungguan City, Guangdong Province, China
Facility Technology (Dongguan) Co., Ltd.

Taiwan
TAZMO Apprecia Formosa Inc.

Hong Kong
Facility (HK) Co., Ltd.

Shanghai
TAZMO Apprecia Electronics Inc.
Shanghai TAZMO Precision Machinery Co., Ltd.

San Francisco
TAZMO INC.

Shaoxing City, Zhejiang Province, China
TAZMO Semitec Shaoxing Technology Co., Ltd.

Vietnam
TAZMO VIETNAM CO.,LTD.
FACILITY HANOI CO.,LTD.

- | | | | | | |
|------|---|--|------|---|--|
| 1972 | ● | - TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment. | 2009 | ● | - Developed 10th generation compatible full-color filter manufacturing system; production and sales started. - Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment. |
| 1980 | ● | - Began production of molding dies, including injection molding dies. - Completed development of Fully-automated Photo Resist Coater; production and sales started. | 2013 | ● | - Apprecia Technology Inc. became our wholly owned subsidiary company. - VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam. |
| 1989 | ● | - Developed TFT Full-color filter manufacturing system; production and sales started. | 2017 | ● | - Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company. |
| 1990 | ● | - Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama - Developed and produced Ultra Compact Transfer System for Super Clean Room. | 2018 | ● | - Listed on the First Section of the Tokyo Stock Exchange |
| 1994 | ● | - Began production and sales of Emboss Carrier Tape. | 2019 | ● | - Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama |
| 1995 | ● | - Began production of injection Molding Products. | 2020 | ● | - Merged with Apprecia Technology Inc. |
| 2001 | ● | - Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started. | 2022 | ● | - TAZMO's listing transferred to Prime Market in Tokyo Stock Exchange. - Increased capital to 3,495,400,000 yen through public offering. - Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China. |
| 2004 | ● | - Listed on the JASDAQ market. | | | |
| 2008 | ● | - Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam. | | | |

We develop, manufacture, and sell equipment for manufacturing cutting-edge semiconductors and packages, manufacturing equipment for organic EL and liquid crystal displays, and clean transfer robots.

Semiconductor Manufacturing Equipment Business Unit

Using the know-how and technology cultivated over 40 years, we provide equipment for various processes such as coating, developing, laminating, and peeling in semiconductor manufacturing worldwide.



Transfer Business Unit

Providing various transport systems that are accurate, speedy, and space-saving, including transport robots for silicon wafers, etc., which are essential for semiconductor manufacturing.



Cleaner Business Unit

Providing silicon wafer cleaning and slurry supply equipment, which is an important process in semiconductor manufacturing, as well as equipment that regenerates and reuses phosphoric acid from waste liquid.



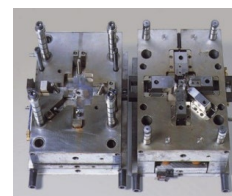
Coater Business Unit

Providing various flat panel manufacturing equipment such as liquid crystal displays. We are currently developing PLP equipment and nanoimprint equipment.



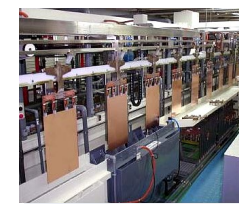
Molding Business

Mold technology, which is essential for parts manufacturing, has been a core technology since our founding, and we provide a variety of products to meet the various needs of user companies.



Surface Treatment Business

Providing plating processing equipment for printed circuit boards incorporated in semiconductor packages and electronic control systems for automobiles, etc.



Attention

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of TAZMO to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

Contact

**Management Plan Div.
TAZMO CO., LTD.**



keiki@tazmo.co.jp